RJ4Q59 Epoxy Formulation

Packaging Adhesive/Sealant

RJR 7340

RJ4Q59 is a B-stage adhesive/sealant for electronic packages. It is ideal for use in automated sealing applications. Formula 7340 has lower chloride content and high performance as adhesive for ceramic and gold plated metal substrates.

Typical Properties of RJ4B	
Max Operating Temperature	160°C
Total ionic content (specific electrical conductance) mS/m	<4.5
Moisture Absorption (24 hr. soak @ 100°C)	<2.0%
Hydrolysable content, ppm (MIL-STD 883H Method 5011.5)	<50
Tg by DSC, °C	74
CTE,ppm/°C	90
Dielectric Constant @ 1 Mhz)	3.3
Volume Resistivity Ohm-cm	$3.5x\ 10^{16}$
Thermal Conductivity W.m-k	0.3-0.4

Typical Sealed Package Performance Properties	
Reflow temperature, °C	260
Thermal cycle (MIL-STD 883E, 1000 cycles @ -50°C/160°C)	pass
Lap shear strength (gold/ceramic @ 25°C), psi	3800

*These values may vary depending upon the materials to which the epoxy is adhered. All above data is based on sealed packages consisting of a ceramic substrate and a ceramic lid.

Sealing and Curing

The recommended curing cycles for clip and bake sealing process is 30 minuets at 120°C followed with 1 hour at 160°C-165°C under 1-5 psi of pressure. Most parts can be sealed and cured in a one-step cycle of 60 minutes at 160°C, under 5 psi of pressure. For alternate curing practices or automated sealing procedures, please consult RJR Technologies Customer Service. (Phone # 510-638-5901 or FAX # 510-638-5958)

Storage and Handling

Shelf life of the material when stored under refrigerated conditions (3-8°C) is 6 months from the date of manufacture. Keep parts in vacuum sealed bag with dry-packs. Room temperature and frozen storage conditions may be appropriate for some applications. Please consult RJR Technologies Customer Service for specific storage options.

Regulatory

This product is RoHS compliant.

Notice

This data is provided for guideline purposes. No warranty is made on the actual use. Customers should perform their own tests.

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